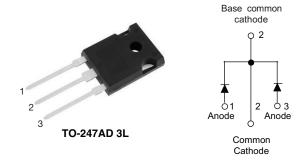


1200 V Power SiC Gen 3 Merged PIN Schottky Diode, 2 x 5 A



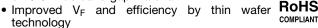
LINKS TO ADDITIONAL RESOURCES



PRIMARY CHARACTERISTICS						
I _F	2 x 5 A					
V_R	1200 V					
V _F at I _F at 25 °C, typ.	1.35 V					
T _J max.	175 °C					
I _R at V _R at 175 °C	3 μΑ					
Q _C (V _R = 800 V)	28 nC					
Package	TO-247AD 3L					
Circuit configuration	Common cathode					

FEATURES

· Majority carrier diode using Schottky technology on SiC wide band gap material





 Positive V_F temperature coefficient, for easy paralleling

- · Virtually no recovery tail and no switching losses
- · Temperature invariant switching behavior
- 175 °C maximum operating junction temperature
- MPS structure for high ruggedness to forward current surge events
- Meets JESD 201 class 1A whisker test
- Solder bath temperature 275 °C maximum, 10 s per JESD 22-B106
- · Material categorization: for definitions of compliance please see www.vishav.com/doc?99912

DESCRIPTION / APPLICATIONS

Wide band gap SiC based 1200 V Schottky diode, designed for high performance and ruggedness.

Optimum choice for high speed hard switching and efficient operation over a wide temperature range, it is also recommended for all applications suffering from Silicon ultrafast recovery behavior.

Typical applications include AC/DC PFC and DC/DC ultra high frequency output rectification in FBPS and LLC converters.

MECHANICAL DATA

Case: TO-247AD 3L

Molding compound meets UL 94 V-0 flammability rating

Base P/N-M3 - halogen-free, RoHS-compliant

Terminals: matte tin plated leads, solderable per

J-STD-002 and JESD 22-B102

Mounting torque: 10 in-lbs maximum

MAXIMUM RATINGS (T _A = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS			
Peak repetitive reverse voltage	V_{RRM}		1200	V			
Continuous forward current, per leg	I _F ⁽¹⁾	$I_F^{(1)}$ $T_C = 158 ^{\circ}C (DC)$		^			
Continuous forward current, per leg	I _F ⁽²⁾	$T_C = 162 ^{\circ}C (DC)$	5	Α			
DC blocking voltage, per leg	V_{DC}		1200	V			
Repetitive peak forward current, per leg	I _{FRM}	$T_C = 25$ °C, f = 50 Hz, square wave, DC = 25 %	32				
Non repetitive peak farward aurae current, per lea	I _{FSM}	$T_C = 25$ °C, $t_p = 10$ ms, half sine wave	42	А			
Non-repetitive peak forward surge current, per leg		$T_C = 110 ^{\circ}\text{C}$, $t_p = 10 \text{ms}$, half sine wave	39				
	P _{tot} (1)	T _C = 25 °C	83	W			
Device discinction needed		T _C = 110 °C	36	1 VV			
Power dissipation, per leg	P _{tot} (2)	T _C = 25 °C	107	w			
		T _C = 110 °C	46	VV			
l ² t value, per leg	∫i ² dt	T _C = 25 °C	8.7	A ² s			
		T _C = 110 °C	7.6	A ^z S			
Operating junction and storage temperatures	T _J ⁽³⁾ , T _{Stg}		-55 to +175	°C			

Notes

- (1) Based on maximum Rth
- (2) Based on typical Rth
- (3) The heat generated must be less than the thermal conductivity from junction-to-ambient: dP_D/dT_J < 1/R_{θJA}



ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)							
PARAMETER SYMBOL TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS		
		I _F = 5 A	-	1.35	1.5		
Forward voltage, per leg	V _F	I _F = 5 A, T _J = 150 °C	-	1.73	2.0	V	
		I _F = 5 A, T _J = 175 °C	-	1.85	-		
	I _R	$V_R = V_R$ rated	-	0.3	30	μΑ	
Reverse leakage current, per leg		V _R = V _R rated, T _J = 150 °C	-	2	80		
		V _R = V _R rated, T _J = 175 °C	-	3	-		
Total conscitance per lea	С	V _R = 1 V, f = 1 MHz	-	307	=.	nE.	
Total capacitance, per leg	C	V _R = 800 V, f = 1 MHz	-	20	-	pF	
Total capacitive charge, per leg	$Q_{\mathbb{C}}$	V _R = 800 V, f = 1 MHz	-	28	-	nC	

THERMAL - MECHANICAL SPECIFICATIONS (T _A = 25 °C unless otherwise specified)							
PARAMETER SYMBOL TEST CONDITIONS MIN. TYP. MAX. UN					UNITS		
Thermal resistance, junction-to-case	per leg	- R _{thJC}		-	1.4	1.8	°C/W
	per device			-	0.7	0.9	°C/W
Marking device				3C10CP12L			

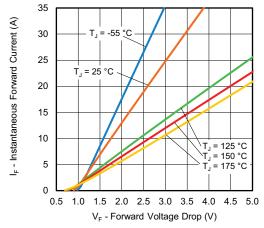


Fig. 1 - Typical Forward Voltage Drop Characteristics, Per Leg

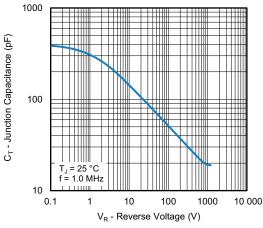


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage, Per Leg

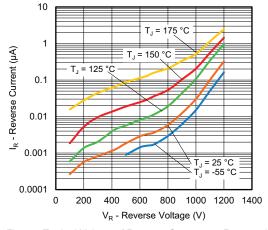


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage, Per Leg

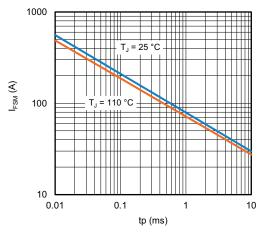


Fig. 4 - Non-Repetitive Peak Forward Surge Current vs. Pulse Duration (Square Wave), Per Leg

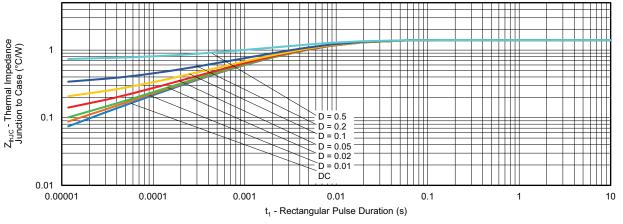


Fig. 5 - Typical Thermal Impedance Z_{thJC} Characteristics, Per Leg

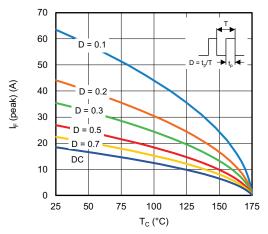


Fig. 6 - Peak Forward Current vs.

Maximum Allowable Case Temperature, Per Leg

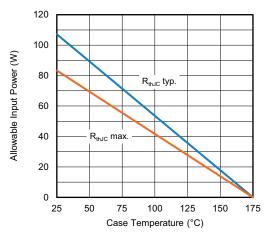


Fig. 7 - Forward Power Loss Characteristics, Per Leg

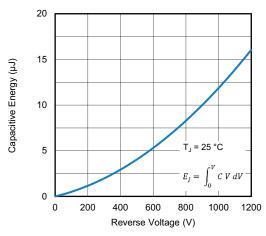


Fig. 8 - Typical Capacitive Energy vs. Reverse Voltage, Per Leg

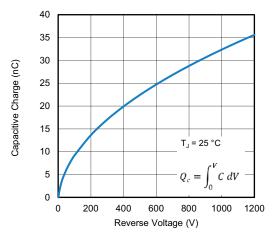
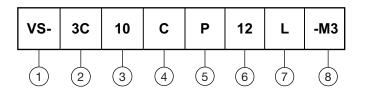


Fig. 9 - Typical Capacitive Charge vs. Reverse Voltage, Per Leg



ORDERING INFORMATION TABLE

Device code



1 - Vishay Semiconductors product

2 - 3C = SiC diode, Generation 3

Current rating (10 = 10 A)

4 - C = common cathode

- P = package TO-247

Voltage rating: (12 = 1200 V)

7 - L = long lead

8 - Environmental digit:

-M3 = halogen-free, RoHS-compliant, and termination lead (Pb)-free

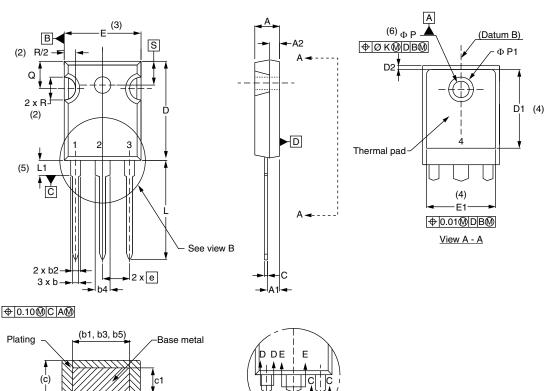
ORDERING INFORMATION		
PREFERRED P/N	BASE QUANTITY	PACKAGING DESCRIPTION
VS-3C10CP12L-M3	25 / tube	Antistatic plastic tubes

LINKS TO RELATED DOCUMENTS				
Dimensions	www.vishay.com/doc?95626			
Part marking information	www.vishay.com/doc?95007			



TO-247AD 3L

DIMENSIONS in millimeters and inches



View B

	MILLIMETERS INCHES				
SYMBOL	IVIILLIIV	IETEKS	INC	NOTES	
	MIN.	MAX.	MIN.	MAX.	
Α	4.65	5.31	0.183	0.209	
A1	2.21	2.59	0.087	0.102	
A2	1.50	2.49	0.059	0.098	
b	0.99	1.40	0.039	0.055	
b1	0.99	1.35	0.039	0.053	
b2	1.65	2.39	0.065	0.094	
b3	1.65	2.34	0.065	0.092	
b4	2.59	3.43	0.102	0.135	
b5	2.59	3.38	0.102	0.133	
С	0.38	0.89	0.015	0.035	
c1	0.38	0.84	0.015	0.033	
D	19.71	20.70	0.776	0.815	3
D1	13.08	-	0.515	-	4

Section C - C, D - D, E - E

SYMBOL	MILLIMETERS		INC	NOTES	
STWIBOL	MIN.	MAX.	MIN.	MAX.	NOTES
D2	0.51	1.30	0.020	0.051	
E	15.29	15.87	0.602	0.625	3
E1	13.46	-	0.53	-	
е	5.46 BSC		0.215 BSC		
ØΚ	0.254		0.010		
L	19.81	20.32	0.780	0.800	
L1	3.71	4.29	0.146	0.169	
ØΡ	3.56	3.66	0.14	0.144	
Ø P1	-	6.98	-	0.275	
Q	5.31	5.69	0.209	0.224	
R	4.52	5.49	0.178	0.216	
S	5.51 BSC		0.217	BSC	

Notes

- (1) Dimensioning and tolerancing per ASME Y14.5M-1994
- (2) Contour of slot optional
- (3) Dimension D and E do not include mold flash. These dimensions are measured at the outermost extremes of the plastic body
- (4) Thermal pad contour optional with dimensions D1 and E1
- (5) Lead finish uncontrolled in L1
- (6) Ø P to have a maximum draft angle of 1.5 to the top of the part with a maximum hole diameter of 3.91 mm (0.154")
- (7) Outline conforms to JEDEC® outline TO-247 with exception of dimension A min., D, E min., Q min., S, and note 4



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